	0.55						
	<specification></specification>						
To :				NQ-SPE-098(00) 23,2022			
	CUSTOM	IER'S PRODUCT NA	ME				
	ASDI PRODUCT NAME:						
	SPAC127N-SERIES						
RECEIPT CONFIRM	ATION						
	ITIONAL CONSENT		CONDITIONAL CO	NSENT			
	APPROVED		CHECKED				
ASDI SIGNATURE							
	APPROVED	CHECKED	PREPARED				
	Xianglong Li	Liang Wang	Jiayin Cai				



Xiamen ASDI Electronics Co.,Ltd.

REV.	DATE	DESCRIPTION	APPROVED	CHECKED	PREPARED
00	Jul.23,2022	New release	Xianglong Li	Liang Wang	Jiayin Cai

CAUTION WHEN HANDLING

Before use the products, please read this specification.

CAUTION FOR SAFETY USING

When use the products, be careful to mentioned below for safety using.

CAUTION *The product should be used within 12 monthes. Focus on the storage conditions. Solderability may become weak if it exceeds the period. *Do not use and store the product in condition of gas corrosion (Salt,Acid,Alkaline). *The products must be preheated before soldering. The operating temperature including self-generated heat must be within '-40~+125 $^\circ$ C Rework by soldering iron: Please keep the mentioned conditions in this specification. *In case of insert P.C. Board on chassis, do not add mechanical stress to the product. *Be careful to arrange of non-magnetic field type inductors. The error may be caused by magnetic field coupling. In case handle the products, please use wrist strap for ground static discharge on human bodv. The product keeps away from magnet or magnetized things. *Do not use the product beyond the mentioned conditions in this specification. *About an application The products listed on this specification sheet are intended for use in general electronic equipment (AV equipment, telecommunications equipment, home appliances, amusement equipment, computer equipment, personal equipment, office equipment, measurement equipment, industrial robots) under a normal operation and use condition. *The products are not designed or warranted to meet the requirements of the applications listed below, whose performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property. Please understand that we are not responsible for any damage or liability caused by use of the products in any of the applications below or for any other use exceeding the range or conditions set forth in this specification sheet. 1)Aerospace/Aviation equipment 6)Transportation control equipment 2)Military equipment 7)Power-generation control equipment 3)Seabed equipment which directly endanger human life 4)Safety equipment 8)Atomic energy-related equipment 5)Medical equipment 9)Other applications that are not considered general-purpose applications If you intend to use the products in the following applications, please contact our sales office. Transportation equipment (cars, electric trains, ships, etc.), Public information-processing equipment, Electric heating apparatus / burning equipment, Disaster prevention/crime prevention equipment When using this product in general-purpose applications, you are kindly requested to take into consideration securing protection circuit/equipment or providing backup circuits, etc., to ensure higher safety. DWG.No. Xiamen ASDI Electronics Co.,Ltd. ISSUE ASDIQ-SPE-098(00)

CUSTOMER	ASDI PART No.	CUSTOMER'S DWG NO.
Each Corporation	SPAC127N-SERIES	

1.SCOPE

Power source inductor for mobile devices such as HDDs, DVCs,DSCs,mobile display panels, portable game devices, compact power supply LCDs, other DC to DC converters

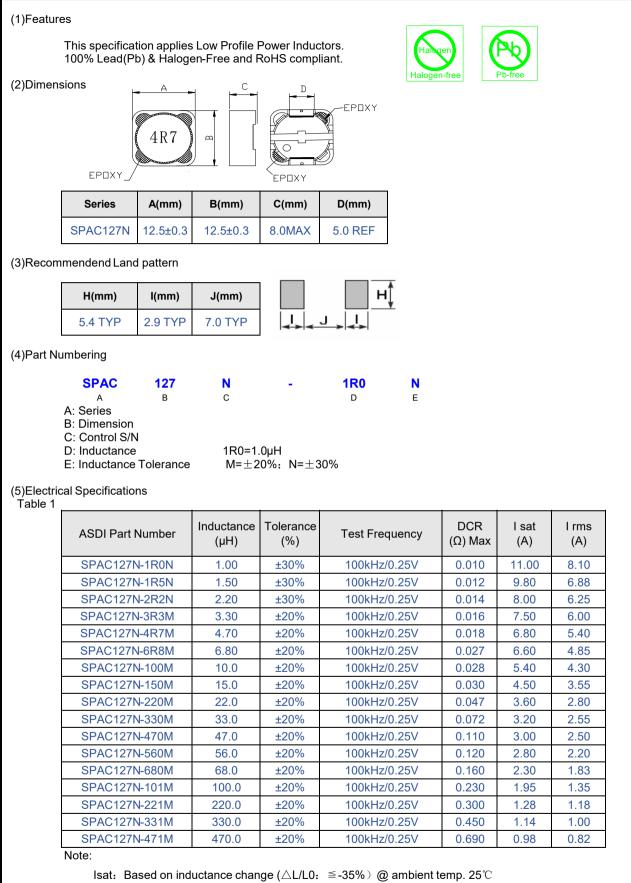
2.INDEX

Listed item	Attachment&Tables	Page
1.Features	Please see (1)	3/6
2.Dimensions	Please see (2)	3/6
3.Recommendend Land pattern	Please see (3)	3/6
4.Part Numbering	Please see (4)	3/6
5.Electrical Specifications	Please see (5)	3/6
6.Reliability Tests	Please see (6)	4/6
7.Soldering	Please see (7)	6/6
8.Packaging Information	Please see (8)	6/6
9.Note	Please see (9)	6/6
10.Standard test conditions		

3.Manufacturing Location

China

	DWG.NO.	ASDIQ-SPE-098(00)	PAGE 2/6	
Xiamen ASDI Electronics Co.,Ltd.				



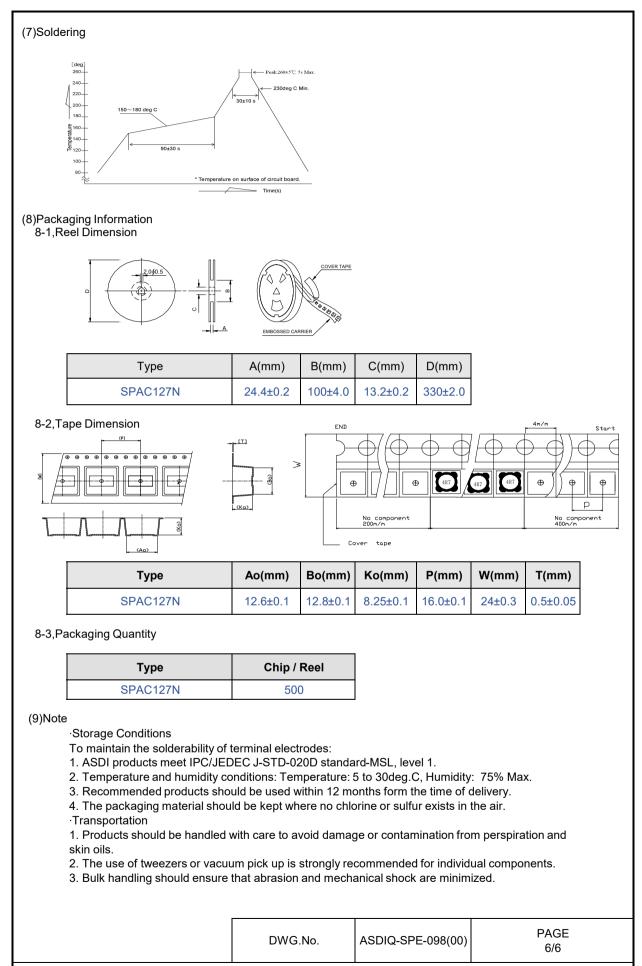
Irms: Based on temperature rise ($\triangle T$: 40°C typ.)

	DWG.No.	ASDIQ-SPE-098(00)	PAGE 3/6		
Xiamen ASDI Electronics Co.,Ltd.					

No. Te	st item	Performance)		Test details
	perating perature	- 40 ~ +125℃		Including self-	generated heat
2 St	torage perature	-40 ~ +85℃. - 5 to 40℃ for the produc			
	ed current	,			
4 Induc	ctance (L)	Within the specified t	olerance	LCR Meter: H 0.25V	P 4285A or equivalent, 100kHz,
5 DC R	Resistance			DC Ohmmete	r: HIOKI3227 or equivalent
	operature acteristics	Inductance change: W	/ithin±20%	temperature ra With reference °C,change rate Measurement temperature ra With reference	of inductance shall be taken at ang within–40 °C to +85 °C. e to inductance value at+20 e shall be calculated. of inductance shall be taken at ang within–40 °C to +125 °C. e to inductance value at+20 e shall be calculated.
7	stance to e substrate	No damage		testing board As illustrated of the arrow in test board rea Substrate size Substrate size Substrate mat Solder cream	below, apply force in the direction dicating until deflection of the ches to 2mm. 10 20 Rod R
8 Te	resion of erminal ectrode	Shall not come off Po	Shall not come off PC board.		I ← S ← S ← S ← S ← S ← S ← S ← S ← S ←
y	stance to bration				les shall be soldered to the test eflow. e submitted to below test 0-55Hz le: 1.5mm (May not exceed 96m/S2) thod:10Hz to 55Hz to 10Hz for s each in X,Y, and Z Direction. east 2hrs of recovery under the ition after the test, followed by tent within 48hrs.
10 Solo	derability				les shall be dipped in flux, and d in molten solder as shown in ol solution containing rosin 25% ature: 245±5℃ ec. oth: All sides of mounting be immersed.
		DWG.No.	ASDIQ-SPE-09	2(00)	PAGE

No.	Test item	Performance	Test details
11	Resistance to soldering		The test sample shall be exposed to reflow oven a 230±5°C for 40 seconds, with peak temperature at 260±5°C for 5 seconds,2 times. Test board thickness: 1.0mm Test board material: glass epoxy-resin
12	Thermal shock		The test samples shall be soldered to the testboard by the reflow.The test samples shall be placed at specifiedtemperature for specified time by step 1 to step 4as shown below in sequence.The temperature cycles shall be repeated 100cycles shall be repeated 100<
13	Damp heat life test	Inductance change: Within±10% No abnormality observed in appearance.	Test Method and Remarks The test samples shall be soldered to the test board by the reflow. The test samples shall be placed in thermostatic oven set at specified temperature and humidity as shown in below. Temperature: 60±2°C Humidity: 90~95%RH Time: 500+24/-0 hrs
14	Loading under damp heat life test		The test samples shall be soldered to the test board by the reflow. The test samples shall be placed in thermostatic oven set at specified temperature and humidity and applied the rated current continuously as shown in below. Temperature: 60±2°C Humidity: 90~95%RH Applied current: Rated current Time: 500+24/-0 hrs
15	Low temperature life test		The test samples shall be soldered to the test board by the reflow. After that, the test samples shall be placed at test conditions as shown in below. Temperature:-40±2°C Time:500+24/-0 hrs
16	Loading at high temperature life test		The test samples shall be soldered to the test board by the reflow. Temperature: 85±2°C. Applied current: Rated current Time: 500+24/-0 hrs.

	DWG.No.	ASDIQ-SPE-098(00)	PAGE 5/6		
Xiamen ASDI Electronics Co.,Ltd.					



Xiamen ASDI Electronics Co.,Ltd.

单击下面可查看定价,库存,交付和生命周期等信息

>>ASDI